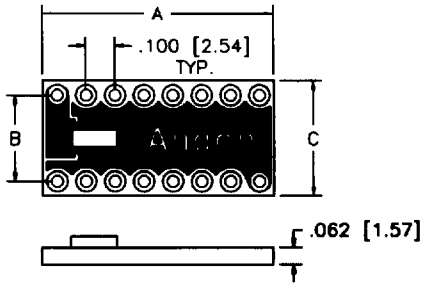


SERIES 451 DECOUPLING CAPACITOR DIP SOCKET (LAMINATE WAFER)



WAFER CHART				
PIN	DIM "A"	"B"	"C"	
6	.300 [7.62]	.300 [7.62]	.400 [10.16]	306
8	.400 [10.16]			308
10	.500 [12.70]			310
14	.700 [17.78]			314
16	.800 [20.32]			316
18	.900 [22.86]			318
20	1.000 [25.40]			320
22	1.100 [27.94]			322
24	1.200 [30.48]	.400 [10.16]	.500 [12.70]	324
28	1.400 [35.56]			328
16	.800 [20.32]			416
22	1.100 [27.94]			422
24	1.200 [30.48]	.600 [15.24]	.700 [17.78]	424
24	1.200 [30.48]			624
28	1.400 [35.56]			628
30	1.500 [38.10]			630
32	1.600 [40.64]			632
36	1.800 [45.72]			636
40	2.000 [50.80]			640
48	2.400 [60.96]			648

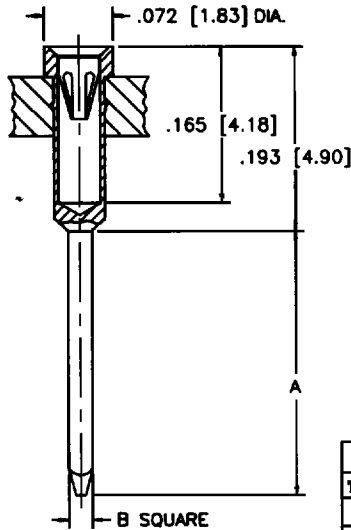


FIG. C

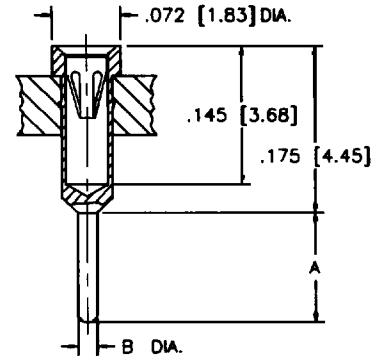
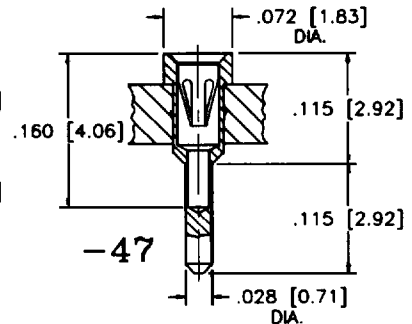
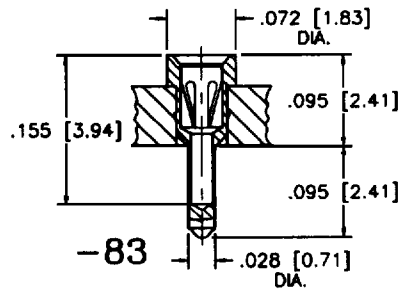


FIG. D

TERMINAL CHART				
TERMINAL	FIG.	DIM "A"	DIM "B"	
-01	D	.115 [2.92]	.020 [0.51]	
-02	C	.370 [9.40]	.025 [0.64]	
-03	C	.510 [12.95]	.025 [0.64]	
-08	D	.170 [4.31]	.020 [0.51]	



CONTACT TYPE

S: STANDARD DIP	INSERTION FORCE	9.0 oz. AVG.
	WITHDRAWAL FORCE	2.0 oz. MIN.
M: STANDARD PGA	INSERTION FORCE	1.8 oz. MAX.
	WITHDRAWAL FORCE	0.5 oz. MIN.
L: INTERSTITIAL PGA	INSERTION FORCE	1.0 oz. MAX.
	WITHDRAWAL FORCE	0.3 oz. MIN.
H: HIGH FORCE	INSERTION FORCE	18.3 oz. MAX.
	WITHDRAWAL FORCE	4.2 oz. MIN.

TECHNICAL SPECIFICATIONS

MATERIAL

INSULATOR COPPER CLAD GLASS EPOXY
FR-4 LAMINATE
UL 94V-0 LISTED
TERMINAL CONTACT BRASS PER ASTM-B16
BeCu PER ASTM-B194
OPERATING TEMP. -65°C TO +140°C

CONTACT FORCES

INSERTION	STANDARD	9 oz. AVG.
WITHDRAWAL	STANDARD	2 oz. MIN.

ORDERING INFORMATION

451-XXX-XXX-PXX-X		CAPACITOR VALUE -1: .004 [0.10] MICROFARAD IS STANDARD -2: .0004 [0.01] MICROFARAD -3: .013 [0.33] MICROFARAD (OTHERS ON REQUEST)
SERIES		
DIP - SPACING		
NO. OF PINS		
TERMINAL STYLE FOR OPTIONAL TERMINAL STYLES SEE TERMINAL STYLES		PLATING: TERMINAL / CONTACT P30: GOLD / GOLD P31: TIN-LEAD / GOLD P32: TIN-LEAD / TIN OTHER PLATINGS AVAILABLE SEE OPTIONAL PLATINGS
CONTACT TYPE		